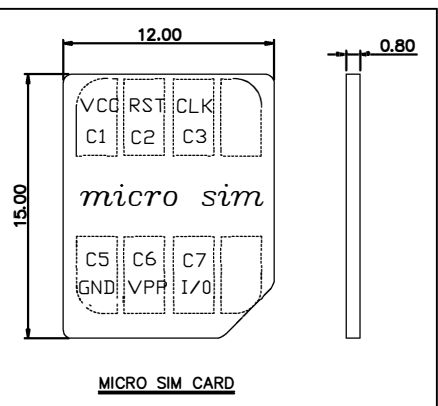
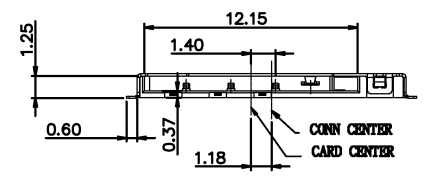
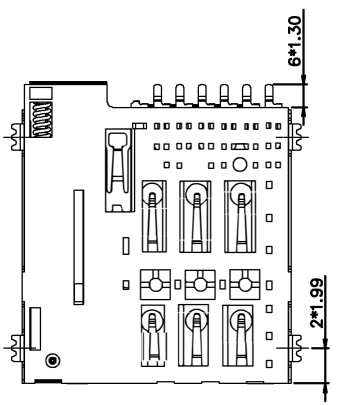
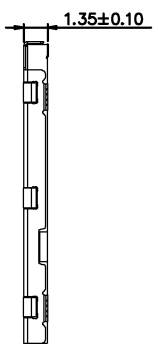
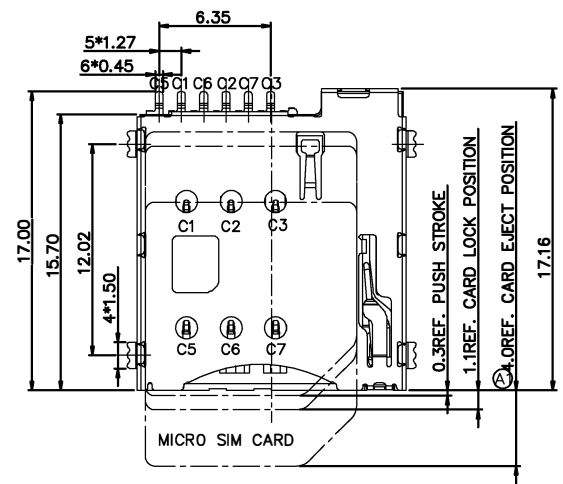
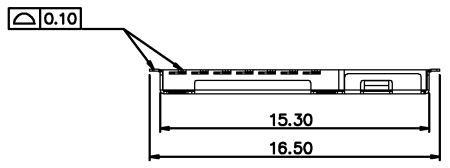
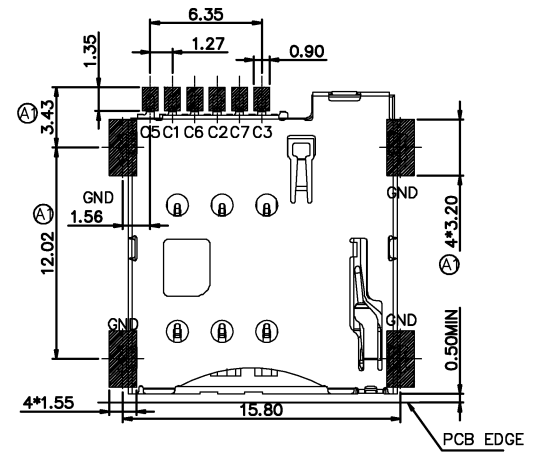


REV	DATE	ECN NO.	MODIFICATION	APPROVER
A	2016/10/14		NEW	Jason_Lee
A1	2017/05/15	RDO0317051501	SIZE CHANGE	Jason_Lee



NOTES:  
**MATERIAL:**  
 Housing: High Temperature thermoplastic,UL94V-0  
 Terminal: Copper Alloy  
 Shell: Stainless  
**SPECIALITY:**  
 Rated Current:0.5A MAX  
 Rated Voltage:50V  
 Ambient Temperature Range:-40°C~+85°C  
 Ambient Humidity Range :95% R.H. Max.  
 Contact Resistance:100mΩ Max  
 Insulation Resistance:1000MΩ/250V DC  
 Dielectric Withstanding Voltage:500V AC  
 Durability:5000 cycles  
 Temperature 260±5°C,

IM pin Assignment	
IN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



█ SMT SOLDER AREA  
 THERE SHOULD NOT BE ANY CIRCUITRIES  
 IN THE LAYOUT SPACE OF THE PRODUCTS  
**RECOMMENDED PCB LAYOUT**  
 GENERAL TOLERANCE±0.05

GENERAL TOLERANCE				UNITS	NAME: MICRO SIM CARD 6P PUSH PUSH		深圳市摩天射频技术有限公司 Shenzhen MyAntenna RF Technology Co.,Ltd
SELECT	TOL	1	2	3	MAT'L	PART NO: MO4-0103540ROA	
X.XXX	±0.10	±0.05	±0.15		FINISH	APPD:	TITLE: MICRO SIM CARD 6P PUSH PUSH SMT H=1.35mm 不带检测脚 无柱
X.XX	±0.15	±0.13	±0.25			CHKD:	A-MicroSIM-1.35A
X.X	±0.20	±0.25	±0.5		Q'TY	DR:	SCALE SHEET REV
X.	±0.30	±0.58	±1.00			JACK	1:1 1/1 A1
ANGLE	±2'						